

C8710M

Conductor

Description

C8710M is an unfritted Ag conductor designed for thick print applications. In a single print and fire application, C8710M yields a thick, dense film that is free from lusters, cracks, and other cosmetic defects. It exhibits excellent solderability and low resistivity. C8710M has good adhesion when printed over a base layer of C4740L or other silver based Heraeus conductors. It is not designed to be used without a base layer. C8710M is an excellent choice for low cost, high conductivity applications that require very thick conductor traces.

Key Features

- Low resistivity Good cosmetics up to 80 µm Excellent solderability



This picture does not show the packaging of C8710M and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Conductivity	≤ 2.2 milliohms/square at 12 µm fired film thickness
Viscosity	180 – 220 Kcps, Brookfield HBT SC4 – 14 spindle and 6R cup at 10 rpm, 25 °
Solids	85 ± 1 %
Alloy Ratio	100
Metal	Ag

Recommended Processing Guide

Printing Parameters	Low resistivity Good cosmetics up to 80 µm Excellent solderability
Drying Temperature	150 °C for 10 - 20 minutes
Process Temperature (TDS)	850°C peak temperature Dwell time of 8-12 minute
Film Thickness	Dried: 100 – 120 µm Fired: 50 – 70 µm (over a 12-14 micron print of C4740L)
Recommended Thinner	RV-507

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Warranty

6 months

Storage

Store in a dry condition at 20 – 25 °C

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